

**IN THE SPECIFICATION**

Replace the paragraph on page 2, lines 18-24 with:

One technique for reading scribe marks is described in U.S. Pat. No. 5,933,521 and involves moving a cassette ~~passed~~ past a fixed reading position of a single stationary camera. Another technique for reading scribe marks is described in U.S. Pat. No. 5,553,168 and involves using a camera to capture a scribe mark image which is then converted from a video signal to a digital signal by a converter. A computer is then used to interpret the digital signal. These scribe readers have a large number of moving parts, use very sophisticated circuitry, and are expensive to maintain and operate.

Replace the paragraph on page 4, lines 14-23 with:

Front support 13 and back support 14 have a lateral dimension indicated by arrows ~~16~~ 21. Front support 13 has a vertical dimension indicated by arrows 22 and back support 14 has a vertical dimension indicated by arrows 27. Lateral dimension 26 of front and back supports 13 and 14, respectively, are preferably the same; however, vertical dimension 27 of back support 14 is greater than vertical dimension 22 of front support 13. In other words, back support 14 is taller than front support 13. Thus, wafer receptacle 11 is angled or beveled with respect to bottom plate 12. By way of example, lateral dimension 26 is 11.5 centimeters (cm), vertical dimension 22 is 5 cm, vertical dimension 27 is 28 cm, and lateral dimension 28 is 20 cm. The dimensions are selected such that the angle formed between wafer receptacle 11 and back support 14 is forty-five degrees.